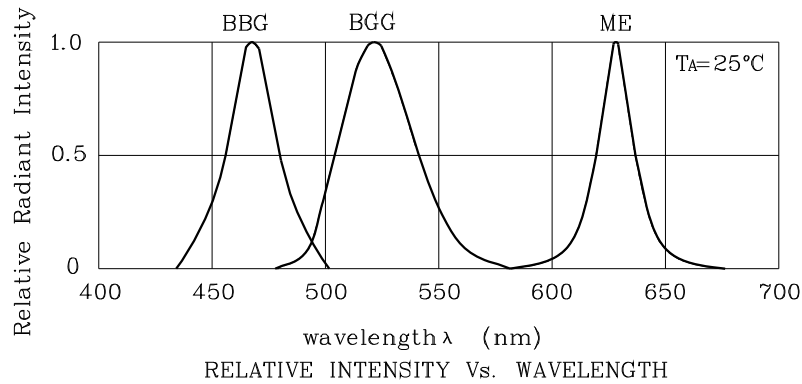
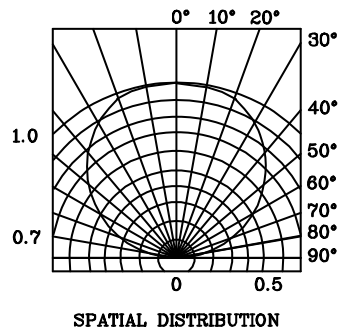
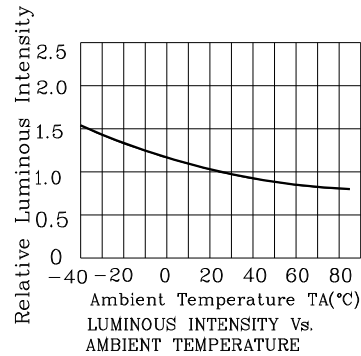
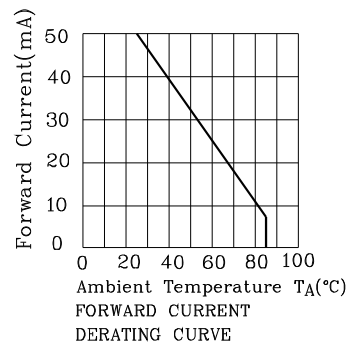
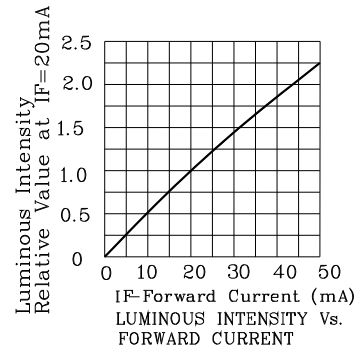
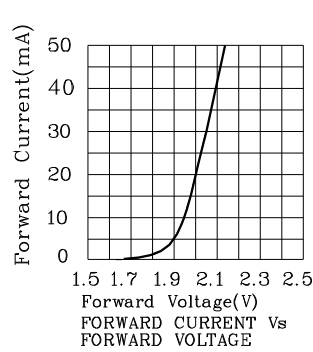


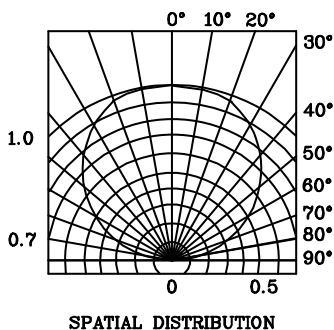
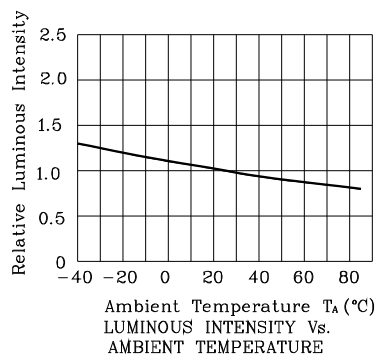
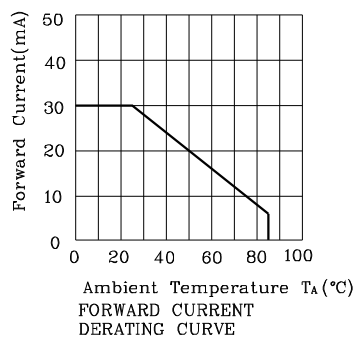
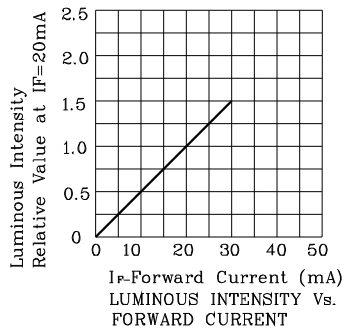
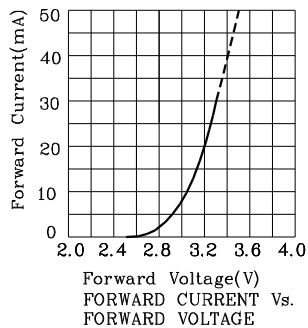
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd	Wavelength nm λ P	Viewing Angle 2 θ 1/2
				min.	typ.	
ZMEBGGBBG45W	Red	InGaAlP	Water Clear	280	397	630
	Green	InGaN		280	497	520
	Blue	InGaN		70	198	468
Published Date : JAN 16 , 2008		Drawing No : SDSA4334		V3	Checked : B.L.LIU	P.1/6



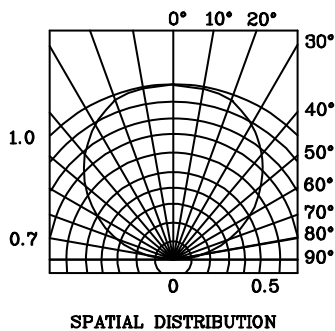
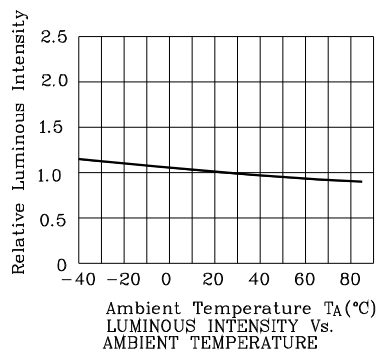
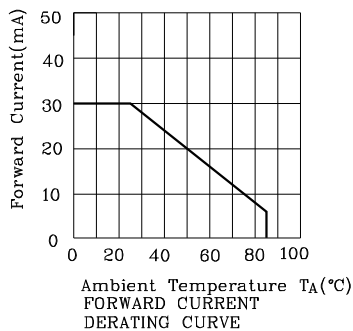
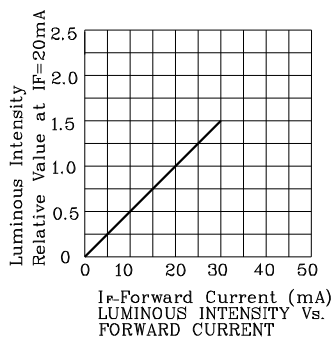
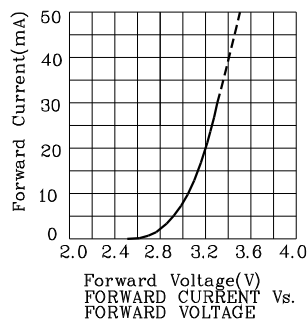
❖ ME



❖ BGG



❖ **BBG**



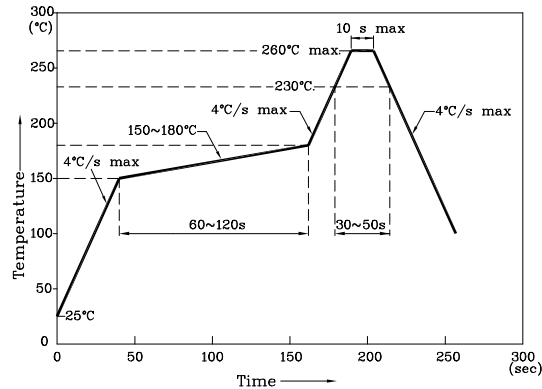
Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity/ luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous intensity/ luminous flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

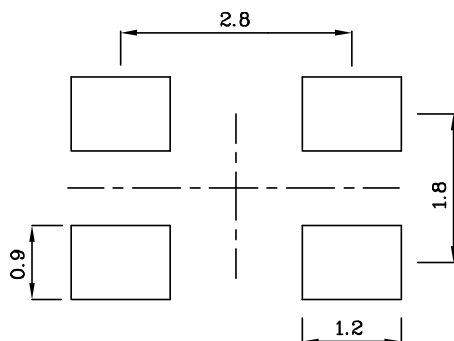
Reflow Soldering Profile For Lead-free SMT Process.



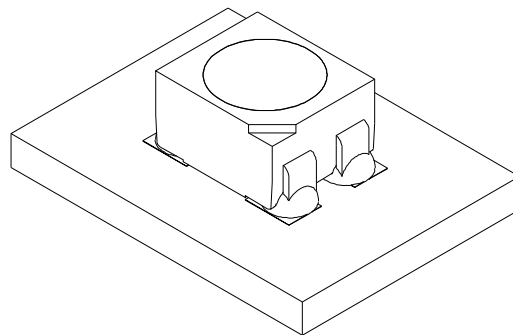
NOTES:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C–260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

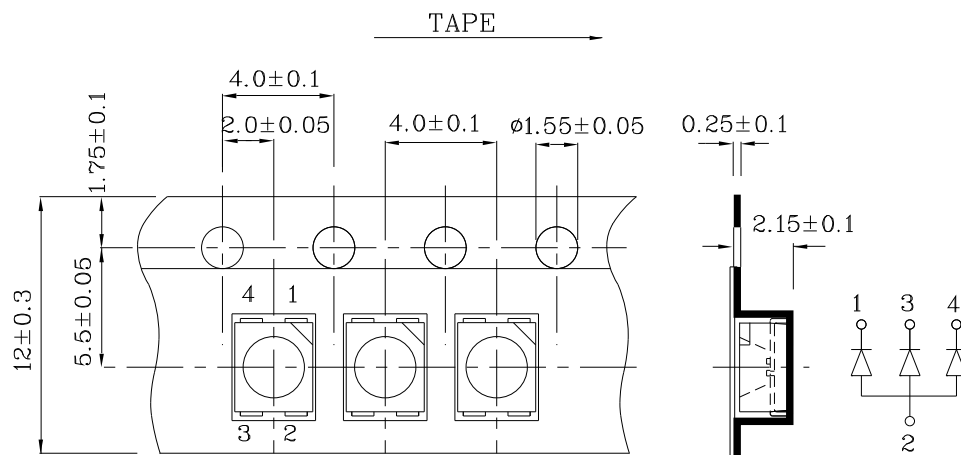
❖ Recommended Soldering Pattern
(Units : mm; Tolerance: ± 0.1)



❖ The device has a single mounting surface. The device must be mounted according to the specifications.

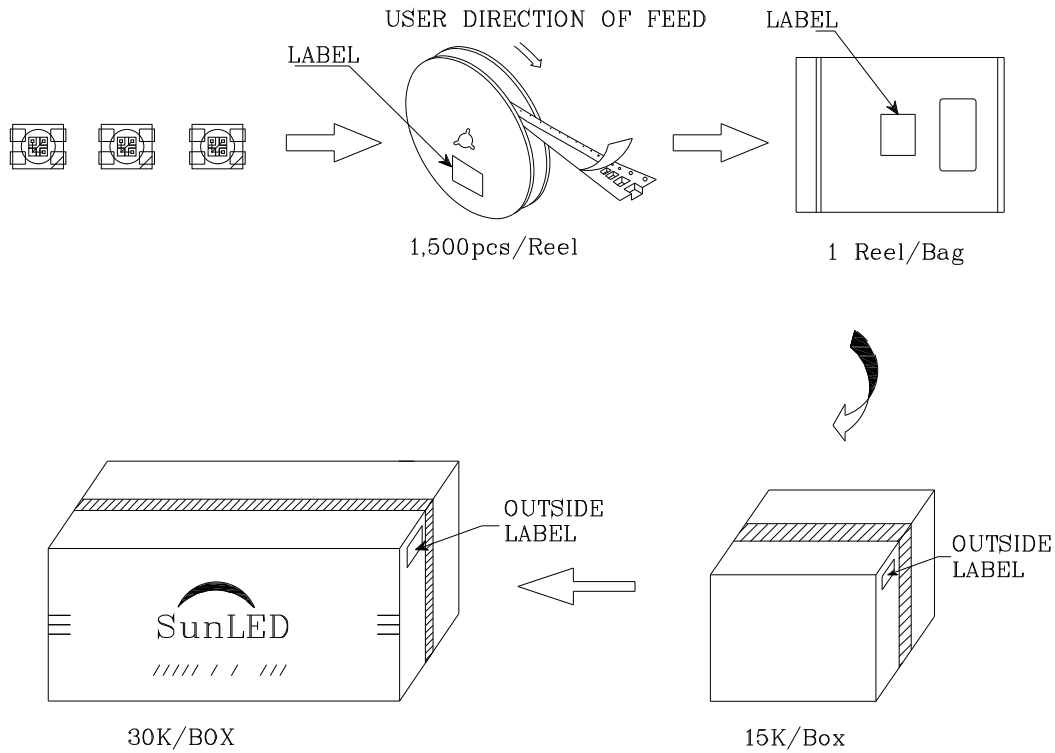


❖ Tape Specification (Units : mm)



PACKING & LABEL SPECIFICATIONS

ZMEBGGBBG45W



		Q.C. Q C XX XX XXXX PASSED
P/NO : Zxxx45x		FQC
QTY : 1,500 pcs	CODE: XXX	
S/N : XX		
LOT NO :		
 XXXXXXXXXXXXXXXXXXXXXXXX		
RoHS Compliant		